

Amendments to Claims

1. (original) A piece of ovenware, comprising, a composition which comprises a mixture of a thermoplastic polymer whose melting point and/or glass transition point is about 250°C or more or a thermoset polymer whose softening point is about 250°C or more, a heating effective amount of a microwave susceptor, provided that said composition has a thermal conductivity of about 0.70 W/m°K or more when measured through a plane of said composition.

2. (original) The ovenware as recited in claim 1 wherein at least a portion of said composition in said ovenware has a thickness of about 100 µm or more.

3. (original) The ovenware as recited in claim 1 also comprising a top which comprises said composition.

4. (original) The ovenware as recited in claim 1 which comprises a top and a bottom.

5. (original) The ovenware as recited in claim 1 wherein said thermoplastic polymer is used.

6. (presently amended) The ovenware as recited in claim 6 5 wherein said thermoplastic polymer is a liquid crystalline polymer.

7. (original) The ovenware as recited in claim 1 wherein said thermal conductivity is about 2.0 W/m°K or more.

8. (original) The ovenware as recited in claim 1 further comprising water vapor escape channels.

9. (presently amended) The ovenware as recited in claim 1 additionally comprising a filler which is not a susceptor and having a thermal conductivity of about 20 W/m°K or more.

10. (original) The ovenware as recited in claim 1 wherein said susceptor comprises graphite.

11. (original) A piece of ovenware, comprising a composition which comprises a mixture of a thermoplastic polymer whose melting point and/or glass transition point is about 250°C or more, or a thermoset polymer whose softening point is about 250°C or more, and a heating effective amount of a microwave susceptor, wherein at least part of said composition is in the form of an insert.

12. (original) The ovenware as recited in claim 11 wherein at least a portion of said composition in said ovenware has a thickness of about 100 µm or more.

13. (original) The ovenware as recited in claim 11 also comprising a top which comprises said composition.

14. (original) The ovenware as recited in claim 11 which is a top.

15. (original) The ovenware as recited in claim 11 wherein said thermoplastic polymer is present and is a liquid crystalline polymer.

16. (original) The ovenware as recited in claim 11 wherein said insert further comprises water vapor escape channels.

17. (original) The ovenware as recited in claim 11 wherein said microwave susceptor comprises graphite.

18. (original) A process for cooking in a microwave oven, comprising, contacting an item to be cooked with a composition which comprises a mixture of a thermoplastic polymer whose melting point and/or glass transition point is about 250°C or more or a thermoset polymer whose softening point is about 250°C or more, a heating effective amount of a microwave susceptor, provided that said composition has a thermal conductivity of about 0.70 W/m²K or more when measured through a plane of said composition, and exposing food in contact with said composition to microwave radiation.

19. (original) The process as recited in claim 18 wherein at least a portion of said composition in said ovenware has a thickness of about 100 μm or more.

20. (original) The process as recited in claim 18 wherein said thermoplastic polymer is used.

21. (original) The process as recited in claim 20 wherein said thermoplastic polymer is a liquid crystalline polymer.

22. (original) The process as recited in claim 18 wherein said thermal conductivity is about 2.0 W/m²K or more.

23. (presently amended) The process as recited in claim 18 wherein cookware comprising said composition has ~~further comprises~~ water vapor escape channels.

24. (original) The process as recited in claim 18 wherein said microwave susceptor comprises graphite.

25. (original) The process as recited in claim 18 wherein cookware comprising said composition is reused in said process.

26. (original) The process as recited in claim 18 wherein a pizza is cooked and/or heated during said process.

27. (new) The process as recited in claim 18 wherein said composition additionally comprises a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.

28. (new) The process as recited in claim 20 wherein said composition additionally comprises a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.

29. (new) The ovenware as recited in claim 11 additionally comprising a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.

30. (new) The ovenware as recited in claim 5 additionally comprising a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.

31. (new) The ovenware as recited in claim 6 additionally comprising a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.

32. (new) The ovenware as recited in claim 7 additionally comprising a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.

33. (new) The process as recited in claim 22 additionally comprising a filler which is not a susceptor and having a thermal conductivity of about 20 W/m[°]K or more.